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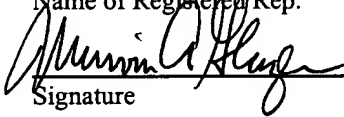
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2 EXAMINER: N. PAREKH ) Art Unit 2811  
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APPLICANT: PETER ELENIUS, ET AL.  
SERIAL NO.: 09/575,298  
FILED: May 19, 2000  
FOR: "SOLDER BAR FOR HIGH POWER FLIP CHIPS"

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box Non-Fee Amendment, Commissioner for Patents, Washington, D.C. 20231 on: April 28, 2003

Marvin A. Glazer  
Name of Registered Rep.

 April 28, 2003  
Signature Date

**AMENDMENT**

Box Non-Fee Amendment  
Honorable Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed on January 28, 2003, please amend the above-identified patent application as follows:

**IN THE CLAIMS:**

Please replace claim 16 with the following amended version:

16. (Three Times Amended) A reflowable solder bar formed upon an upper surface of a first substrate, the first substrate having a first electrical contact, said reflowable solder bar being adapted to join the first electrical contact to a second electrical contact on a second substrate, said reflowable solder bar comprising in combination:

a. a first generally circular solder pad formed upon the upper surface of the first

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